

N-Channel Logic Level Enhancement Mode Field Effect Transistor

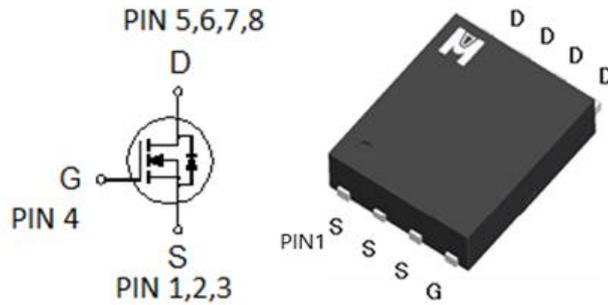
Product Summary:

$BV_{DSS}$	30V
$R_{DS(on)}$ (MAX.)	2.3m $\Omega$
$I_D$	100A

N Channel MOSFET

UIS, Rg 100% Tested

RoHS & Halogen Free & TSCA Compliant



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$T_C = 25^\circ\text{C}$	$I_D$	100	A
	$T_C = 100^\circ\text{C}$		70	
Pulsed Drain Current <sup>2</sup>		$I_{DM}$	400	
Avalanche Current		$I_{AS}$	65	
Avalanche Energy	$L = 0.1\text{mH}, I_D = 65\text{A}, R_G = 25\Omega$	$E_{AS}$	211	mJ
Repetitive Avalanche Energy <sup>3</sup>	$L = 0.05\text{mH}$	$E_{AR}$	105	
Power Dissipation	$T_C = 25^\circ\text{C}$	$P_D$	50	W
	$T_C = 100^\circ\text{C}$		20	
Operating Junction & Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

100% UIS testing in condition of  $V_D = 25\text{V}, L = 0.1\text{mH}, V_G = 10\text{V}, I_L = 40\text{A}$ , Rated  $V_{DS} = 30\text{V}$  N-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		2.5	$^\circ\text{C} / \text{W}$
Junction-to-Ambient <sup>4</sup>	$R_{\theta JA}$		50	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle < 1%

<sup>3</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz.

Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

<sup>4</sup>Guarantee by Engineering test



ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.5	3	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	μA
		V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125 °C			25	
On-State Drain Current <sup>1</sup>	I <sub>D(ON)</sub>	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 10V	100			A
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 25A		2.0	2.3	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 15A		2.9	3.7	
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 25A		70		S
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz		3813		pF
Output Capacitance	C <sub>oss</sub>			540		
Reverse Transfer Capacitance	C <sub>rss</sub>			440		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 15mV, V <sub>DS</sub> = 0V, f = 1MHz		1.5		Ω
Total Gate Charge <sup>1,2</sup>	Q <sub>g</sub> (V <sub>GS</sub> =10V)	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 25A		59		nC
	Q <sub>g</sub> (V <sub>GS</sub> =4.5V)			28		
Gate-Source Charge <sup>1,2</sup>	Q <sub>gs</sub>			13		
Gate-Drain Charge <sup>1,2</sup>	Q <sub>gd</sub>			11		
Turn-On Delay Time <sup>1,2</sup>	t <sub>d(on)</sub>		V <sub>DS</sub> = 15V, I <sub>D</sub> = 5A, V <sub>GS</sub> = 10V, R <sub>G</sub> = 3Ω		8.5	
Rise Time <sup>1,2</sup>	t <sub>r</sub>			11.3		
Turn-Off Delay Time <sup>1,2</sup>	t <sub>d(off)</sub>			55.1		
Fall Time <sup>1,2</sup>	t <sub>f</sub>			28.3		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>c</sub> = 25 °C)</b>						
Continuous Current <sup>4</sup>	I <sub>S</sub>				100	A
Pulsed Current <sup>3</sup>	I <sub>SM</sub>				400	
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = 25A, V <sub>GS</sub> = 0V			1.2	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = I <sub>S</sub> , dI <sub>F</sub> /dt = 100A / μS		35		nS
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>			200		A
Reverse Recovery Charge	Q <sub>rr</sub>			25		nC

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

<sup>3</sup>Pulse width limited by maximum junction temperature.

<sup>4</sup>Package Limited.



Ordering & Marking Information:

Device Name: EMP21N03HR for EDFN 5 x 6



→ P21N03R: Device Name

→ ABCDEFG: Date Code

A: Assembly House

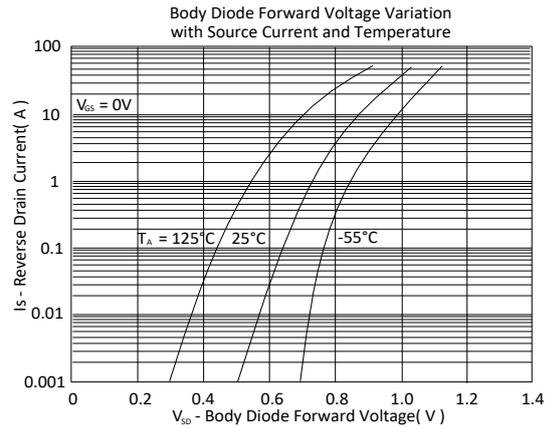
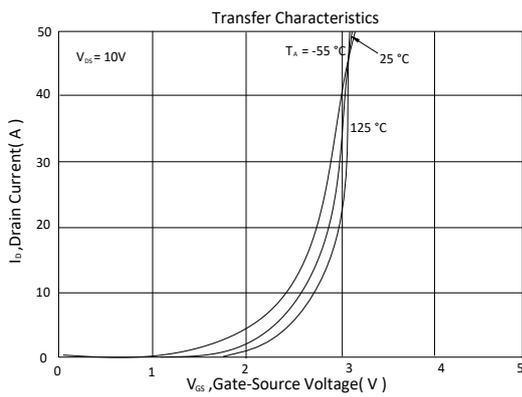
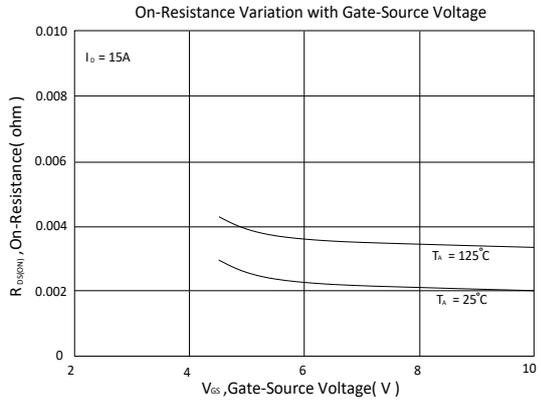
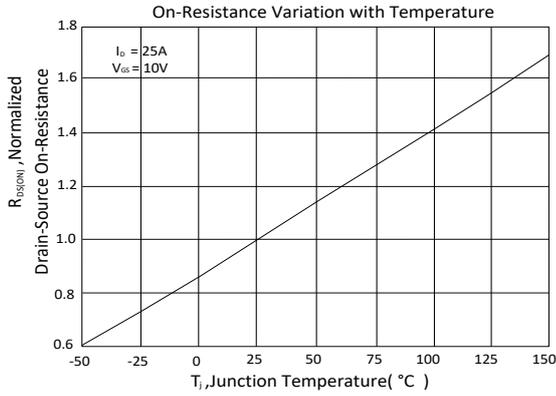
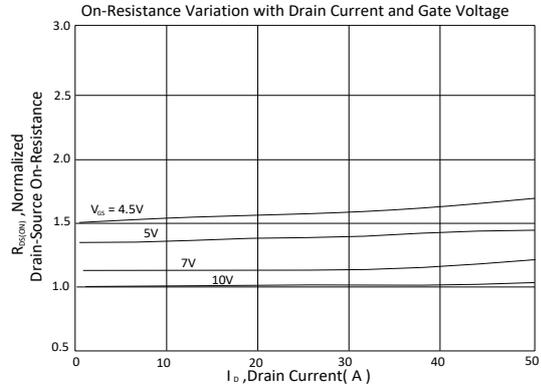
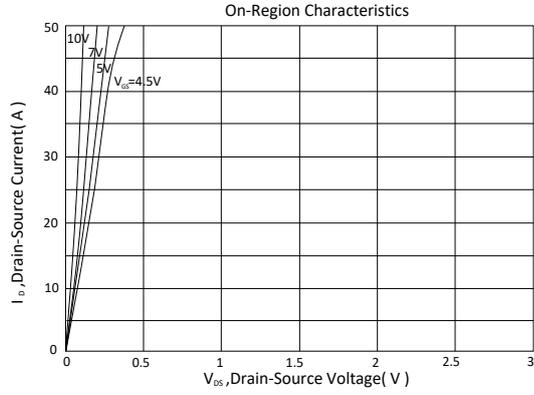
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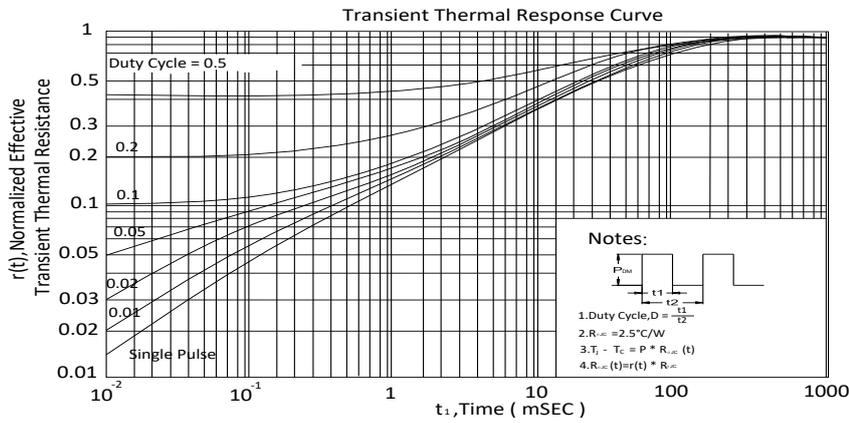
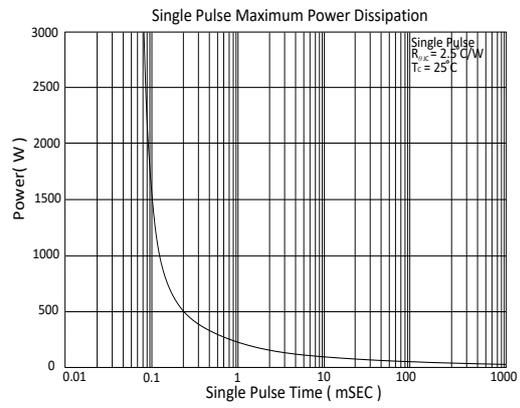
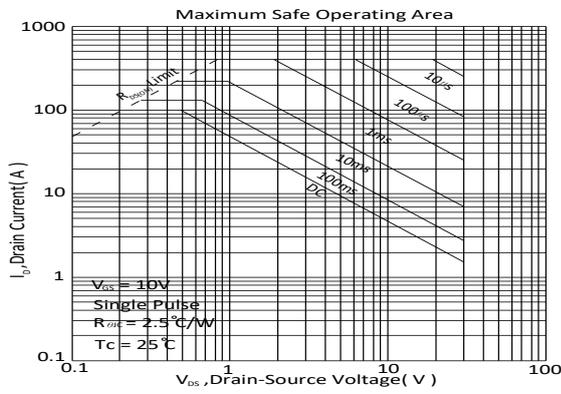
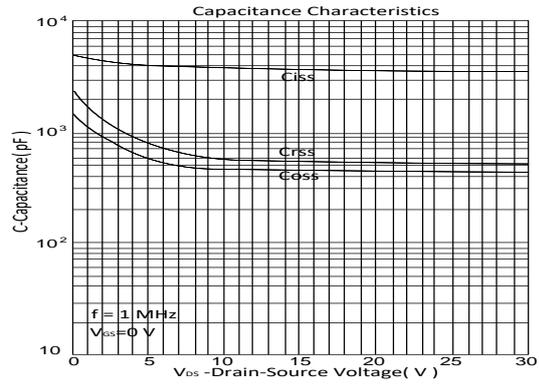
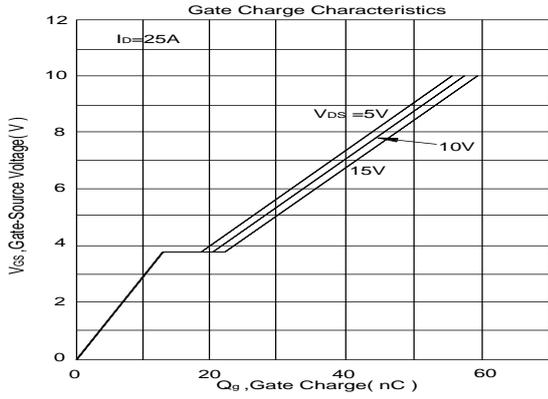
C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)

DEFG: Serial No.



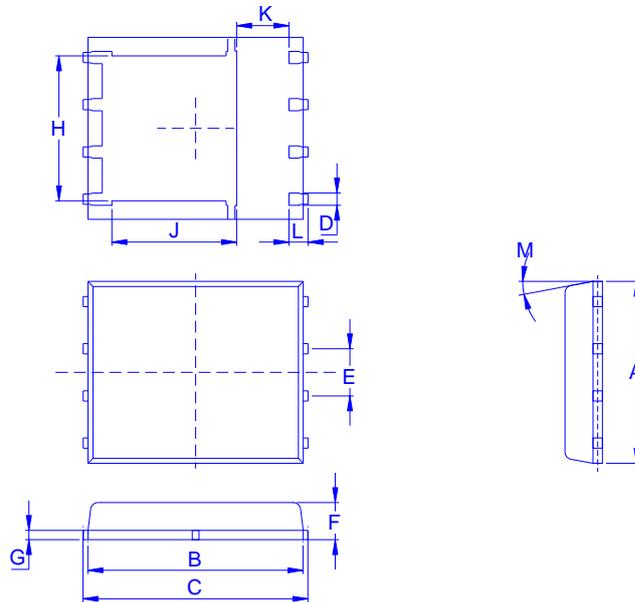
TYPICAL CHARACTERISTICS







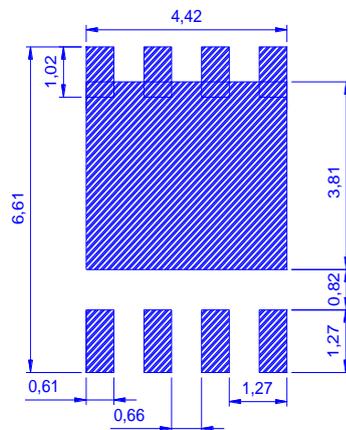
Outline Drawing



Dimension in mm

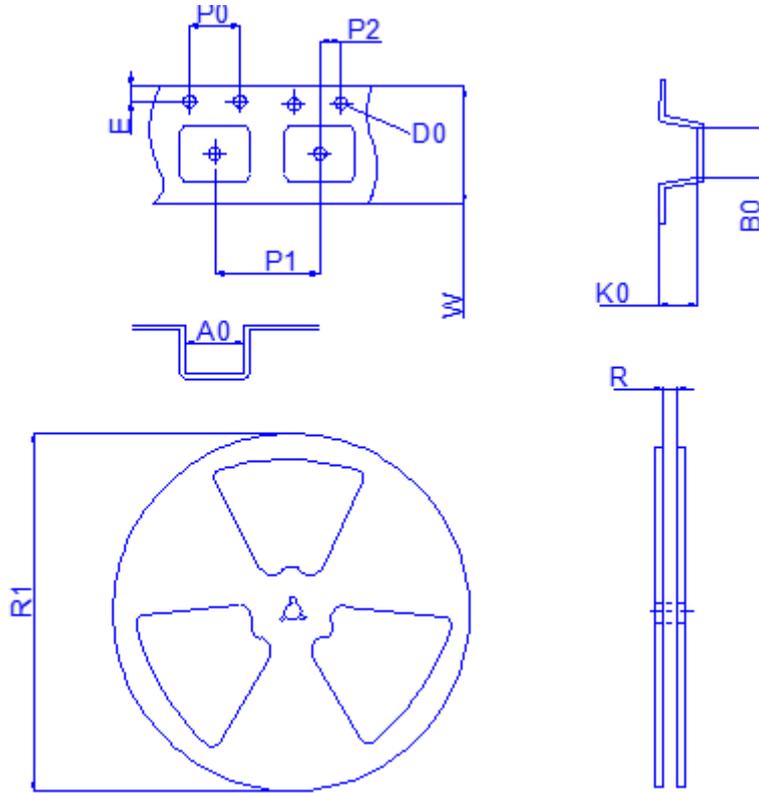
Dimension	A	B	C	D	E	F	G	H	J	K	L	M
Min	4.8	5.55	5.9	0.3	1.17	0.85	0.15	3.61	3.18	1	0.38	0°
Typ.	4.9	5.7	6	0.4	1.27	0.95	0.2	3.87	3.44	1.2	0.4	
Max	5.4	5.85	6.15	0.51	1.37	1.17	0.34	4.31	3.78	1.39	0.71	12°

Recommended minimum pads





Tape&Reel Information:2500pcs/Reel



Package	EDFN5X6
Reel	13"
Device orientation	<p>FEED DIRECTION</p> <p>→</p>

Dimension in mm

Dimension	Carrier tape									Reel	
	A0	B0	D0	E	K0	P0	P1	P2	W	R	R1
Typ.	6.4	5.3	1.5	1.8	1.6	4	8	2	12	12.4	330
±	0.2	0.2	0.1	0.1	0.6	0.1	0.1	0.1	0.3	2	2